# Welcome to the CHIPS Incentives Program Portal

Use this portal to apply for CHIPS Incentives or submit a Statement of Interest. To get started or to log in to an existing account, click on the button in the upper right corner of the screen.

This portal supports the National Institute of Standards and Technology, a bureau of the U.S. Department of Commerce, in the administration of the CHIPS Incentives Program, which is part of CHIPS for America (https://www.chips.gov). The CHIPS Incentives Program can provide direct funding (via grants, cooperative agreements, or other transactions), loans, and loan guarantees (collectively, "CHIPS Incentives") for eligible projects.

Learn more (https://nist.gov/chips/notice-funding-opportunity-commercial-fabrication-facilities) about the program objectives and requirements applicants will need to meet to receive funding.





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Before you apply, please read the CHIPS Incentives Program Notice of Funding Opportunity (NOFO) for Commercial Fabrication Facilities (https://nist.gov/chips/notice-funding-opportunity-commercial-fabrication-facilities). The NOFO provides detailed information about the program objectives and requirements applicants will need to meet to receive funding. It also describes the procedures the Department will use to evaluate and select applications for funding.

Resources (8)	
Workforce Development and Child Care Planning Guide	
Additional guides and templates	
Sam.gov	
Informational Webinars	
Frequently Asked Questions	
Grants.gov	
Vision for Success: Commercial Fabrication Facilities	

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Resources

**User Support** 

## **User Support**

For issues related to the CHIPS Incentives Portal such as logging in, adding additional users, navigating the website or application intake system, uploading forms or templates, please contact apply@chips.gov.

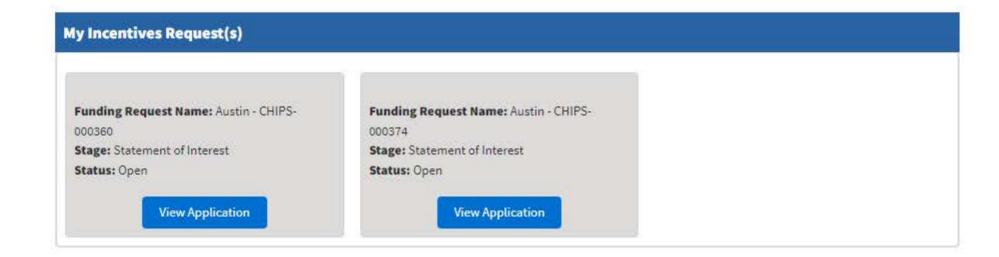
For program-related questions, including program guidelines in the Notice of Funding Opportunity (NOFO), the application or application forms and templates, questions on program eligibility including eligible program costs or activities, the application review process, program technical assistance, please contact the program team at apply@chips.gov.

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Welcome, Austin Fadely



Start Your Submission

Any communication, data, or other information stored or transmitted on this system may be disclosed or used for any lawful Government purpose. This includes, but is not limited to, statutorily required disclosures to other Executive Branch agencies or offices,

Congress, and the U.S. Government Accountability Office pursuant to 15 U.S.C § 4652.

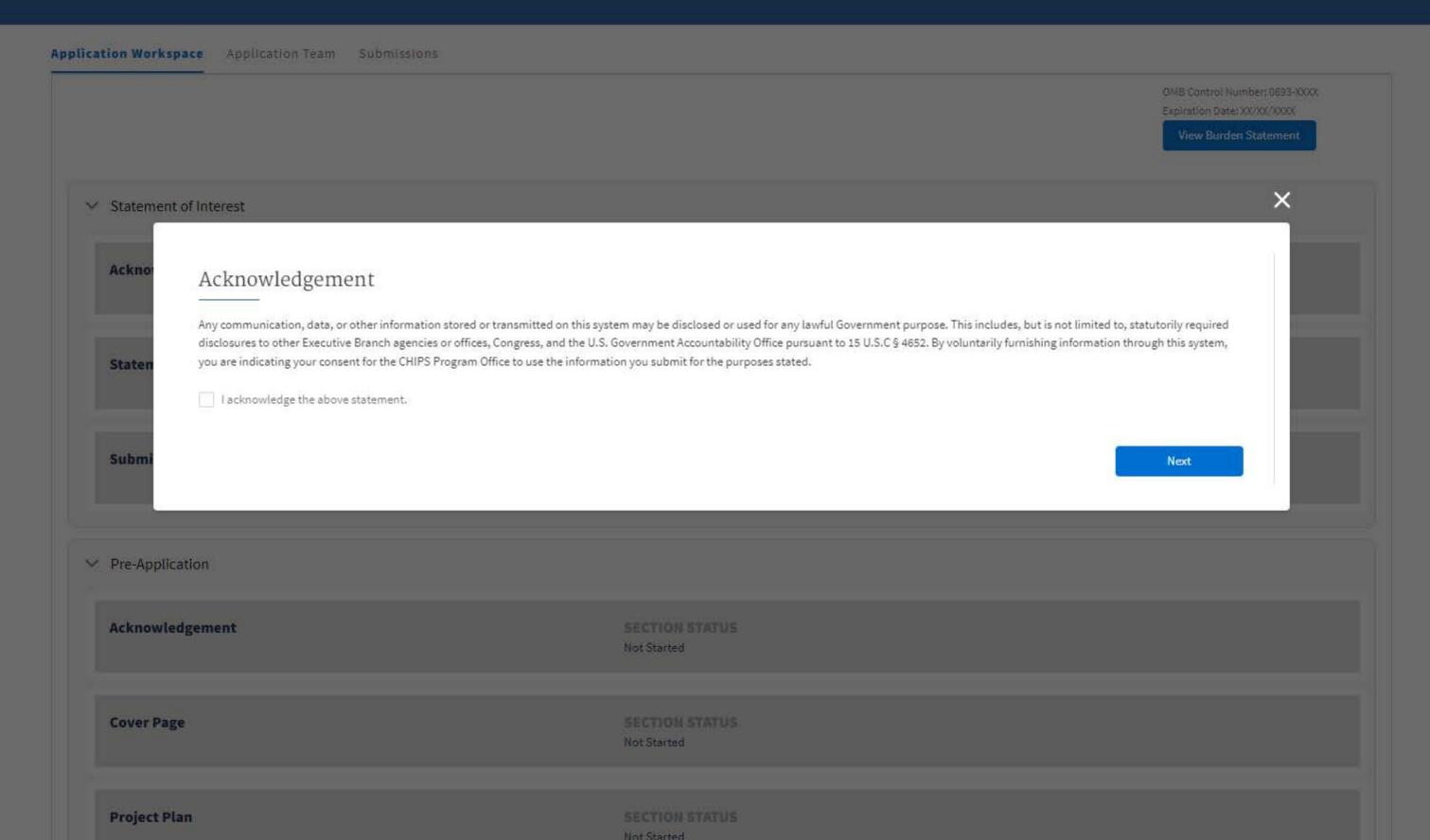
By voluntarily furnishing information through this system, you are indicating your consent for the CHIPS Program Office to use the information you submit for the purposes stated.

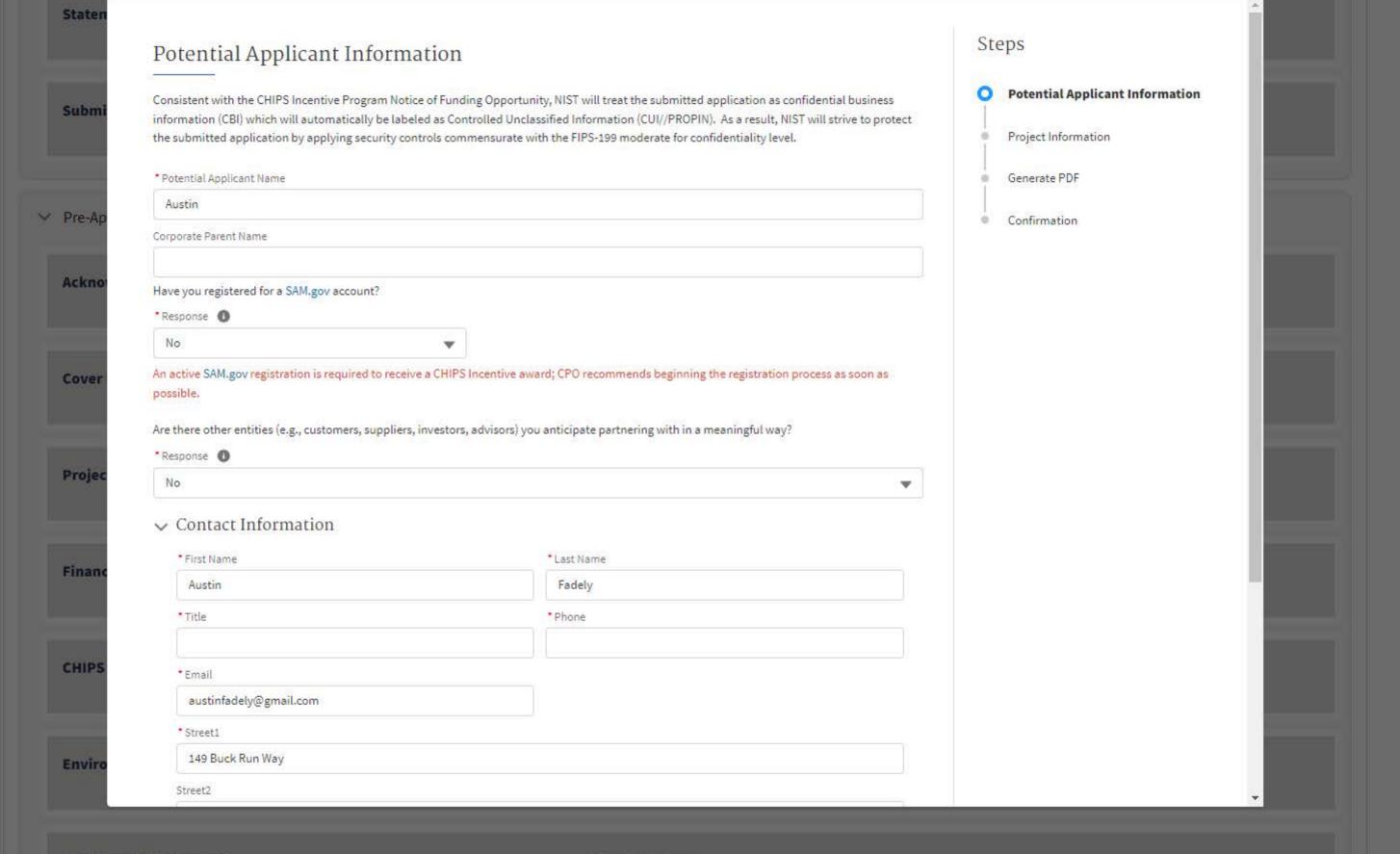
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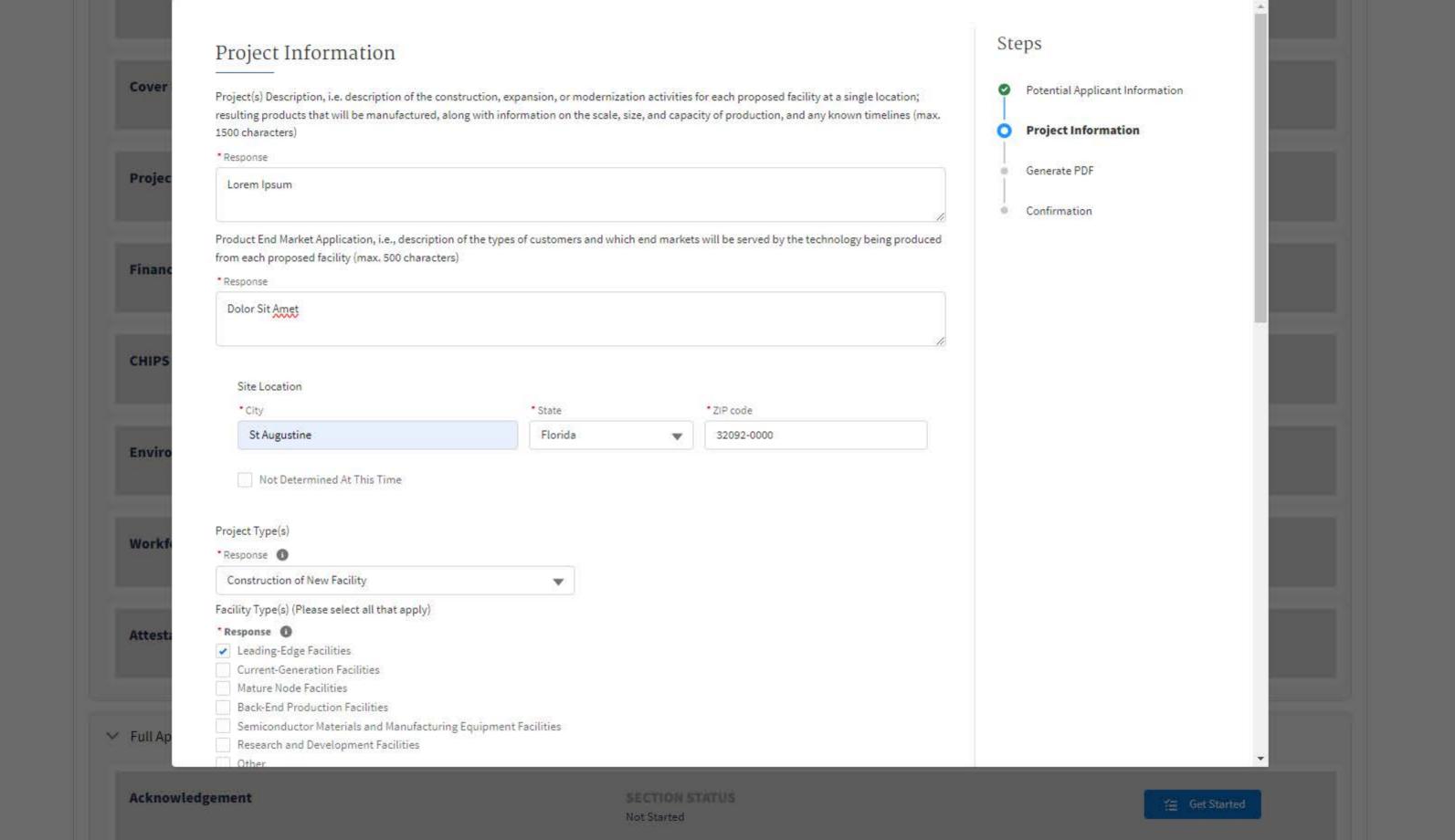
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Resources







	Research and Development F	racilities				
Ackno	Other					-
ACKHO	If other, please specify					-
Cover	Product Information - Leading-Edge Facilities selected  Technology Segment (Leading-Edge Facilities)  *Response					
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	*Minimum 1	*Maximum 🚯				
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CHIPS	Estimated peak monthly unit pro	duction capacity (e.g. wafers per month, comp		<i>J</i>		
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	* Year			25		- 1
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-	Is there any other inform	ation about the potential application	n that we should know? (max. 1500 characte	ers)		- 10
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### Attest and Submit

#### Use of Information

Information submitted in the Statement of Interest (SOI) is being provided to the U.S. Department of Commerce (DOC) for informational and planning purposes. Any information contained in the SOI will not become part of any subsequent application package or be used as part of the award review and selection process; further, the contents of this submission shall not be considered binding and the potential applicant may change any information provided in the SOI as part of any subsequent Pre-Application and Full Application submissions.

DOC recognizes the importance of protecting confidential business information and will follow applicable laws to protect such information, including, for example, the CHIPS Act, the Trade Secrets Act, and the Freedom of Information Act. Please refer to Section IV.C of the CHIPS Incentives Program – Commercial Fabrication Facilities Notice of Funding Opportunity (CHIPS-CFF NOFO) for a further discussion of these laws. By submitting this SOI, the potential applicant represents that it has read Section IV.C of the CHIPS-CFF NOFO information and acknowledges and agrees that the information contained in the SOI may be used by DOC in accordance with that section.

#### **Submission Certifications**

**Public Communications** 

#### Steps

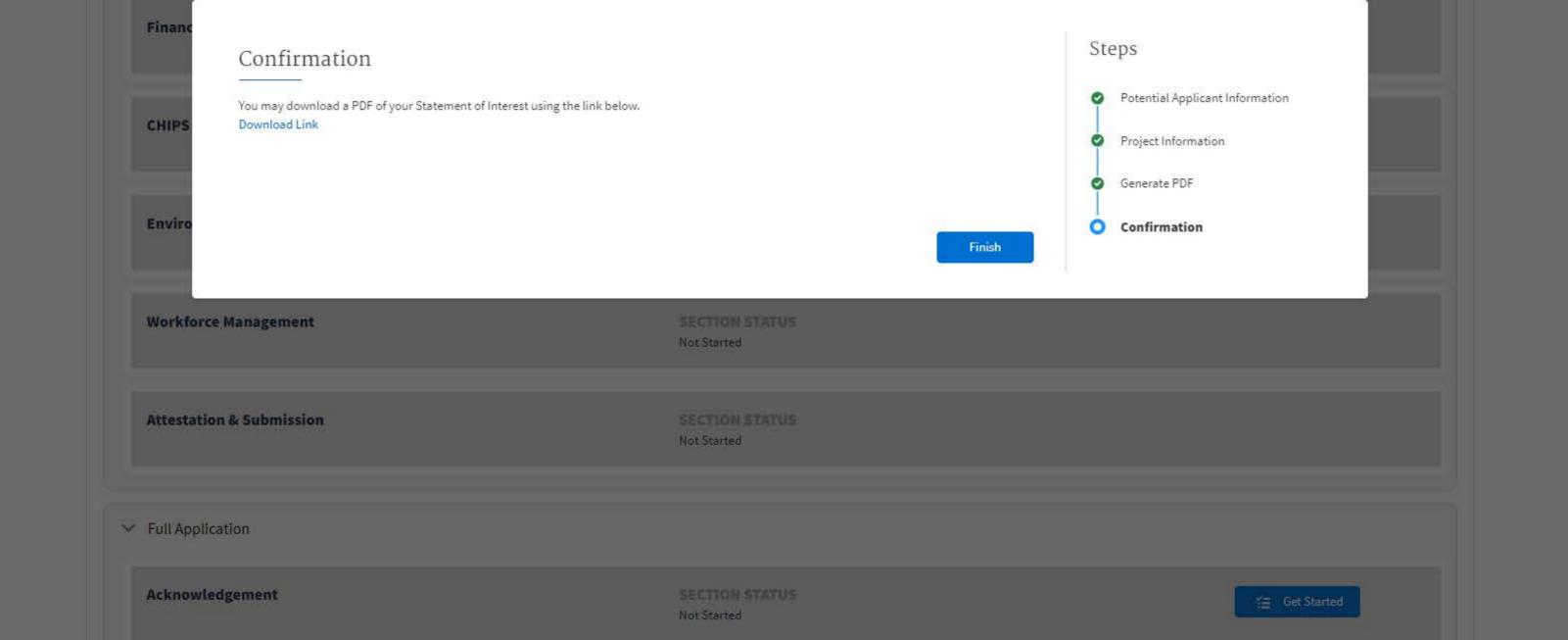
Attest and Submit

Generate PDF

Confirmation

Staten	DOC recognizes the importance of protecting confidential business information and will follow applicable laws to protect such information, including, for example, the CHIPS Act, the Trade Secrets Act, and the Freedom of Information Act. Please refer to Section IV.C of the CHIPS Incentives Program – Commercial Fabrication Facilities Notice of Funding Opportunity (CHIPS-CFF NOFO) for a further discussion of these laws. By submitting this SOI, the potential applicant represents that it has read Section IV.C of the CHIPS-CFF NOFO information and acknowledges and agrees that the information contained in the SOI may be used by DOC in accordance with that section.	
Ackno	Submission Certifications	
Addition	Attestation	
Staten	The individual submitting the SOI certifies on behalf of the potential applicant that the data an information submitted and the representations made in this submission are true and correct, to the best of the potential applicant's knowledge as of the date of submission	
Submi		-
	Attestation	-
Pre-Ap	The individual submitting the SOI further certifies that they possess the full legal authority to submit this SOI on behalf of the potential applicant	
Ackno		-
	Public Communications	_
Cover	Attestation	-
Projec	The individual submitting the SOI acknowledges that neither the potential applicant nor its affiliates may issue any press release or otherwise publicly disclose the status of the SOI or the contents of any communications with DOC without DOC's prior written consent	
	*	
	Next	

Not Started



Incentives CHIPS Program

